

Upcoming: June 15–18, 1997 Intl. Workshop on Superconductivity, ISTEC '97, MRS; June 15–19, INTERpack '97: The ASME Intl., Intersociety Electronic and Photonic Packaging Conf., Endorsed; June 16–20, ICAM '97/E-MRS '97 Spring Meeting, E-MRS/IUMRS.

To list an event in the Calendar, contact J. Meiksin, Materials Research Society, 9800 McKnight Road, Pittsburgh, PA 15237-6006; 412-367-3004 ext. 522; fax 412-367-4373.

MRS, A-MRS, C-MRS, E-MRS, MRS-I, MRS-J, MRS-K, MRS-R, MRS-T, M-MRS, or IUMRS at the end of an entry indicates sponsorship or co-sponsorship of an event by the International Union of Materials Research Societies or one of its adhering bodies. "Endorsed" identifies events endorsed by MRS.

▼ identifies a new or revised entry this month.

See the March 1997 MRS BULLETIN for May 1997 Calendar entries.

JUNE 1997

1–4 2nd Greek-Italian Intl. Conf. on New Laser Technologies and Applications, *Ancient Olympia, Greece*. A. Carabelas, Solonos 12, Kastellokambos, 26442 Patra, Greece; fax 0030-61-991626.

1–4 15th Conf. on Crystal Growth and Epitaxy, *Fallen Leaf Lake, CA*. J.E. Huffman, Rockwell Science Ctr., 3370 Miraloma Ave., HA 17, Anaheim, CA 92803; 714-762-4011; e-mail jehuffman@anet.rockwell.com.

2–5 1997 Intl. Conf. on GaAs Manufacturing Technology, *San Francisco, CA*. B. Hewitt, Northrup Grumman Corp., P.O. Box 1521, MS 3K13, Baltimore, MD 21203; 410-765-1964, fax 410-765-7370; e-mail hewitt.b.s@postal.essd.northgrum.com.

2–7 Microspheres—Microcapsules Technology Workshop, *Moscow, Russia*. N. Borisenko; fax 007-095-938-2251; e-mail ngbor@sci.lpi.msk.su.

4–6 4th Intl. Symposium on Sputtering and Plasma Processes, *Kanazawa, Japan*. Y. Chijimatsu, ISSP '97 Secretariat, Japan Technology Transfer Assoc., Dai-ni Koujimachi Bldg. 2F Koujimachi 4-2, Chiyoda-ku, Tokyo 102, Japan; 81-3-3238-5300; fax 81-3-3238-5388; e-mail XLD04163@niftyserve.or.jp.

4–6 4th Intl. Workshop on Stress-Induced Phenomena in Metallizations, *Tokyo, Japan*. Hidekazu Okabayashi, NEC Corporation, Research and Development Group, Miyukigaoka 34, Tsukuba 305, Japan; 81-298-50-1105; e-mail okabayas@lbr.cl.nec.co.jp.

8–11 7th European Workshop on Metal-Organic Vapor Phase Epitaxy and Related Growth Techniques, *Berlin, Germany*. U. Knospe, Secretary, Heinrich-Hertz-Inst. für Nachrichtentechnik Berlin GmbH, Einsteinufer 37, D-10587 Berlin, Germany; 49-30-31002-557; fax 49-30-31002-558; e-mail knospe@mails.hhi.de.

8–12 ▼ 5th Intl. Seminar on Highly Conducting Organic Materials for Molecular Electronics, *Poznan-Puszczykowo, Poland*. A. Graja, Inst. of Molecular Physics, Polish Academy of Sciences, Smoluchowskiego 17, 60-179 Poznan, Poland; 48-61-612475; fax 48-61-684524; e-mail graja@ifmpan.poznan.pl.

8–12 Intl. Biotechnology Meeting, *Houston, TX*. Massachusetts Biotechnology Council, 245 First St., 14th Floor, Cambridge, MA 02142; 617-577-8198; fax 617-577-7860; http://www.massbio.org.

8–13 1997 IEEE MTT-S Intl. Microwave Symposium, *Denver, CO*. V. Nair, Technical Program Chair, 602-413-5922; fax 602-413-5934; e-mail v.nair@ieee.org; http://www.ieee.org/mtt/mtt.html.

8–13 3rd Mediterranean Workshop and Meeting on Novel Optical Materials and Applications, *Cetraro, Italy*. C. Umerton, Dipartimento di Fisica, Univ. della Calabria, 87036 Rende (CS), Italy; fax 39-984-839389; e-mail umerton@fis.unical.it.

8–20 NATO Advanced Study Inst. on Applications of Superconductivity, *Loen, Norway*. H. Weinstock, AFOSR/NE, Bolling AFB, DC 20332-8080; fax 202-767-4986; e-mail harold.weinstock@afosr.af.mil.

9–11 3rd Intl. Conf. on Computers in Biomedicine, *Terni (Umbria), Italy*. P. Doughty-Young, BIOMED 97 Conf. Secretariat, Wessex Inst. of Technology, Ashurst Lodge, Ashurst, Southampton SO40 7AA, UK; 44-1703-293223; fax 44-1703-292853; e-mail paula@wessex.witcmi.ac.uk; http://www.witcmi.ac.uk.

9–14 25th Intl. Meeting on Chemical Engineering, Environmental Protection, and Biotechnology, *Frankfurt am Main, Germany*. DECHEMA e.V., Ausstellungenstagungen, Postfach 15 01 04, D-60061 Frankfurt am Main, Germany; 49-69-7564-0; fax 49-69-7564-201.

10–12 Fundamental Research Needs in Ceramics, *Washington, DC*. L.J. Schioler, Ceramics Program Director; 703-306-1836; fax 703-306-0515; e-mail lschiol@nsf.gov.

11–13 3rd Recycling of Metals Conf., *Barcelona, Spain*. B. Roudebush, ASM Intl. European Office, Blvd. St. Michel 15, B-1040 Brussels, Belgium; 32-2-7431546; fax 32-2-7431550; e-mail 100332.670@compuserve.com.

11–13 4th Intl. Colloquium on Process Simulation, *Espoo, Finland*. P. Attila, Helsinki Univ. of Technology, TKK-V, FIN-02150 Espoo, Finland; 358-0-451-2768; fax 385-0-451-2799; e-mail ari.jokilaakso@hut.fi; http://www.hut.fi/ltk/jauhe/mt96cfd.html.

15–18 1997 Intl. Workshop on Superconductivity, *ISTEC '97, The Big Island, HI*. Dr. Tetsuji Kobayashi, Director, Intl. Affairs Dept., ISTEC 34-3, Shimabashi 1-chome, Minato-ku, Tokyo 105, Japan; 81-3-3431-4004; fax 81-3-3431-4044; e-mail kokusai@istec.mxa.meshnet.or.jp. **MRS.**

15–18 Symposium on Quantum Theory and Simulation of Bulk, Surface and Interface Phenomena, *Raleigh, NC*. QTS Symposium, College of Physical and Mathematical Sciences, North Carolina State Univ., Box 8201, Raleigh, NC 27695-8201; e-mail qts@ncsu.edu; http://www2.ncsu.edu/ncsu/pams/qts.

15–19 4th Intl. Special ASME Intl. Symposium on Superalloys 718, 625, 706, and Derivatives, *Pittsburgh, PA*. E.A. Loria, Alloy 718-625-706 Committee, 1828 Taper Dr., Pittsburgh, PA 15241; 412-221-5905; fax 412-221-7355.

15–19 **INTERpack '97: The ASME Intl., Intersociety Electronic and Photonic Packaging Conf., Honolulu, HI**. AT&T Bell Laboratories, Basic Research, Physical Science and Engineering Div., 600 Mountain Ave., Rm. 7D-326, Murray Hill, NJ 07974; 908-582-5301; fax 908-582-5570; e-mail suhir@hoggpa.att.com. **Endorsed.**

15–20 8th Intl. Symposium on Nondestructive Characterization of Materials, *Boulder, CO*. D. Harris, Center for Nondestructive Evaluation, 102 Maryland Hall, 3400 N. Charles St., The Johns Hopkins Univ., Baltimore, MD 21218-2689; 410-516-5397; fax 410-516-7249; e-mail cnde@jhvmms.hcf.jhu.edu.

16–19 30th Intl. Symposium on Automotive Technology and Automation, *Florence, Italy*. ISATA, 32A Queen St., Croydon, CR0 1SY, UK; 44-181-6813069; fax 44-181-6861490; e-mail 100270.1263@compuserve.com; http://www.spincom.com/isata.

16–19 Intl. Chemical and Petroleum Industry Inspection Technology V Conf., *Houston, TX*. American Society for Nondestructive Testing, 1711 Arlingdale Lane, P.O. Box 28518, Columbus, OH 43228-0518; 614-274-6003; fax 614-274-6899; http://www.asnt.org.

16–20 7th European Conf. on Applications of Surface and Interface Analysis, *Göteborg, Sweden*. I. Olefjord, ECASIA '97, Chalmers Univ. of Technology, Dept. of Engineering Metals, S-412 96, Göteborg, Sweden; fax 46-31-7721262; e-mail olefjord@em.chalmers.se; http://www.em.chalmers.se/ecasia/ecasia97.htm.

16–20 **ICAM '97/E-MRS '97 Spring Meeting, Strasbourg, France**. P. Siffert, E-MRS 1997 Spring Meeting, BP20, 67037 Strasbourg Cedex 2, France, 33-03-88-10-65-43; fax 33-03-88-10-62-93; e-mail EMRS@FRCPN11.IN2P3.FR. **E-MRS/IUMRS.**

18–19 3rd Annual Environmental Sampling, On-Site Analysis, and Sample Preparation Conf., *Pittsburgh, PA*. H. Nowicki, PACS, Inc., 409 Meade Dr., Coraopolis, PA 15108; 800-367-2587; fax 412-457-1214.

18–20 TRI/Princeton Workshop on Characterization of Porous Materials: From Angstroms to Millimeters, *Princeton, NJ*. A.V. Niemark, TRI/Princeton, 601 Prospect Ave., Princeton, NJ 08542-0625; 609-924-3150; fax 609-683-7149; e-mail aniemark@triprinceton.org; http://pluto.njcc.com/~aniemark/copm_workshop.

25–27 3rd Synthesis, Processing and Modeling of Advanced Materials Conf., *Paris, France*. B. Roudebush, ASM Intl. European Office, Blvd. St. Michel 15, B-1040 Brussels, Belgium; 32-2-7431546; fax 32-2-7431550; e-mail 100332.670@compuserve.com.

25–27 39th Electronic Materials Conf., *Ft. Collins, CO*. TMS Customer Service Dept., 420 Commonwealth Dr., Warrendale, PA 15086; 412-766-9000; fax 412-776-3770; e-mail csc@tms.org.

25–27 Fractals In Engineering, *Arcachon, France*. Conf. Secretariat, INRIA Rocquencourt, Relations Exterieurs, Bureau des cours et colloques, B.P. 105, 78153 LE CHESNAY Cedex, France; 33 1 39 63 50 53; fax 33 1 39 63 56 38; e-mail FE97@inria.fr; http://www.rocq.inria.fr/fractales/FE97.html.

26–28 6th Intl. Superconductive Electronics Conf., *Berlin, Germany*. ISEC '97 Conf. Secretariat, Dipl. Phys. Silvia Knappe, Phys.-Techn. Bundesanstalt, Abbestr. 10-12, 10587 Berlin, Germany; fax 49-30-3481490; e-mail isec97@ptb.de; http://www.ptb.de/isec97/start.htm.

26–28 Superconducting Materials Aspects: Research and Technology, *Liège, Belgium*. C. Lacrosse, Conf. Secretary, A.I.M. rue St. Gilles 31, B-4000 Liège, Belgium; 32-4-222-2946; fax 32-4-222-2382; e-mail aimulg@misc.ulg.ac.be.

29–2 ▼ 1997 Intl. Conf. on Powder Metallurgy and Particulate Materials, *Chicago, IL*. Metal Powder Industries Federation, 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523.

29–5 3rd Intl. Workshop in Russia: Fullerenes and Atomic Clusters, *IWFAC '97, St. Petersburg, Russia*. A-Ya. Vul', Chair, Ioffe Physico-Technical Inst., 26 Polytechnicheskaya, 194021 St. Petersburg, Russia; 007-812-5156774; fax 007-812-2470073; e-mail fuller@vul.ioffe.rssi.ru.

30–3 3rd European Conf. on Applied Superconductivity, *Veldhoven, The Netherlands*. Convention Bureau Basics, P.O. Box 217, 7500 AE, Enschede, The Netherlands; 31-53-4894444; fax 31-53-4894442; e-mail a.spierenburg@basics.utwente.nl.

JULY 1997

1–3 3rd Intl. Conf. on Computational Methods in Contact Mechanics, *Madrid, Spain*. L. Kerr, Contact Mechanics 97 Conf. Secretariat, Wessex Inst. of Technology, Ashurst Lodge, Ashurst, Southampton SO40 7AA, UK; 44-1-703-293223; fax 44-1-703-292853; e-mail liz@wessex.ac.uk; http://www.wessex.ac.uk.

2-4 Ultrasonics Intl. Conf., *Delft, The Netherlands*. S. Emsley, Ultrasonics 97, Elsevier Science Ltd., The Boulevard, Langford Lane, Kidlington, Oxon OX5 1GB, UK; 44-1865-843721; fax 44-1865-843958; e-mail s.emsley@elsevier.co.uk; <http://www.msc.cornell.edu/~ui97>.

6-9 Intl. Meeting on Low-Temperature Microscopy and Analysis, *Oxford, England*. Royal Microscopical Society, 37/38 St. Clements, Oxford OX4 1AJ, UK; 44-18-65-248768; fax 44-18-65-791237.

7-11 Intl. Conf. on Applied Nonlinear Dynamics near the Millennium, *San Diego, CA*. e-mail andm97@dracula.ucsd.edu.

7-11 Thermomechanical Processing of Steels and Other Materials, *Wollongong, Australia*. ASM Intl., Member Services Center, Materials Park, OH 44073-0002; 216-338-5151; fax 216-338-4634; e-mail memserv@po.asm-intl.org.

10-11 Annual Government Lab/Industry Technology Transfer Conf., *Arlington, VA*. L.W. Sircy, Technology Transfer Conferences, Inc., 325 Plus Park Blvd., #108, Nashville, TN 37217; 615-366-0679; fax 615-366-0695.

13-17 7th Intl. Symposium on Silicon Molecular Beam Epitaxy, *Banff, Canada*. P. Lamoureux, Conf. Mgr., 7th Intl. Symposium on Si-MBE, Natl. Research Council of Canada, Ottawa, Ontario, Canada K1A 0R6; 613-993-9431; fax 613-993-7250; e-mail mbe97@nrc.ca; <http://www.nrc.ca/confserv/mbe97/welcome.html>.

13-18 Intl. Conf. on High Strength Concrete, *Kona, HI*. Engineering Foundation Conf., 345 E. 47th St., New York, NY 10017; 212-705-7836; fax 212-705-7441; e-mail engfnd@aol.com; <http://www.engfnd.org/engfnd>.

14-16 Symposium on Synthesis, Properties, and Applications of High Temperature Superconductors, *Queensland, Australia*. T. Chandra, Dept. of Materials Engineering, Univ. of Wollongong, Wollongong 2522, Australia; fax 61-42-213-112; e-mail t.chandra@uow.edu.au.

15-17 3rd Intl. Conf. on Computer Methods and Experimental Measurements for Surface Treatment Effects, *Oxford, UK*. L. Kerr, Surface Treatment 97 Conf. Secretariat, Wessex Inst. of Technology, Ashurst Lodge, Ashurst, Southampton SO40 7AA, UK; 44-1-703-293223; fax 44-1-703-292853; e-mail liz@wessex.ac.uk; <http://www.wessex.ac.uk>.

19-25 ▼ American Crystallographic Association Annual Meeting, *St. Louis, MO*. American Crystallographic Association, P.O. Box 96 Ellicott Station, Buffalo, NY 14205-0096; 716-856-9600; 716-852-4846; e-mail aca@hwi.buffalo.edu.

19-27 ▼ 3rd Intl. Summer School on High Temperature Superconductivity, *Eger, Hungary*. I. Vajda, Dept. of Electrical Machines and Drives, Technical Univ. of Budapest, Egry Jozsef utca 18, H-1111 Budapest, Hungary; 36-1-463-2961; e-mail vajda@ntb.bme.hu; <http://docs4.mht.bme.hu/~farkas>.

20-23 Intl. Metallographic Society Convention, *Seattle, WA*. ASM Intl., Member Services Center, Materials Park, OH 44073-0002; 216-338-5151; fax 216-338-4634; e-mail memserv@po.asm-intl.org.

21-24 Intl. Microscopy Meeting, *Chicago, IL*. N. Daerr, McCrone Research Inst., 2820 S. Michigan Ave., Chicago, IL 60616-3292; 312-842-7100; fa-312-842-1078; e-mail ndaerr@mcroi.org; <http://www.mcroi.org>.

21-25 19th Intl. Conf. on Defects in Semiconductors, *Aveiro, Portugal*. Doutora Helena Nazaré, Departamento de Física, Universidade de Aveiro, 3810 Aveiro, Portugal; 351-34-370-200; fax 351-34-28-600; e-mail mhnazare@fis.ua.pt or Gordon Davies, Physics Dept., King's College London, The Strand, London WC2R 2LS, England; 44-171-873-2573; fax 44-171-873-2423; e-mail g.davies@kcl.ac.uk.

27-31 Structures Under Extreme Loading Conditions: 1997 ASME Pressure Vessels and Piping Conf., *Orlando, FL*. Y.S. Shin, Dept. of Mechanical Engineering, Naval Postgraduate School, Monterey, CA 93943; 408-656-2568; fax 408-656-2238; e-mail yshin@me.nps.navy.mil.

27-1 13th Intl. Conf. on Ion Beam Analysis, *Lisboa, Portugal*. Conf. Secretariat, IBA-13, Inst. Tecnológico e Nuclear, E.N. 10, 2685 Sacavém, Portugal; 351-1-9550021; fax 351-1-9941525; e-mail IBA13@aiff. ciil.fc.ul.pt.

27-1 ▼ 24th Annual Review of Progress in Quantitative Nondestructive Evaluation, *San Diego, CA*. QNDE Programs, Center for NDE, Iowa State Univ., Applied Sciences Complex II, 1915 Scholl Rd., Ames, IA 50011-3042; 515-294-8152; fax 515-294-7771.

27-1 Intl. Conf. on Magnetism, *Cairns, Australia*. Intl. Conf. on Magnetism, 108 Church St., Hawthorn Victoria, Australia 3122; 61-3-9819-3700; fax 61-3-9819-5978; e-mail icm@meetingplanners.com.au.

27-1 Intl. Symposium on Optical Science, Engineering, and Instrumentation, *San Diego, CA*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; <http://www.spie.org>.

27-1 Joint ICMC-CEC 1997 Conf., *Portland, OR*. Nancy Wilson, Exe-Me and Company, P.O. Box 25445, Portland, OR 97298-0445; 503-292-2114; e-mail ewemeco@europa.com or Bill Warnes, Oregon State Univ., Mech. Engineering Dept., Corvallis, OR 97331-6001; 541-737-7016; e-mail warnesw@engr.orst.edu.

28-1 Cryogenic Engineering Conf./Intl. Cryogenic Materials Conf., *Portland, OR*. CEC/ICMC, P.O. Box 25445, Portland, OR 97225-0445; 503-292-2114; fax 503-292-1375; e-mail jbarclay@me.uvic.ca; <http://www.orst.edu/groups/cec-icmc97>.

28-1 Nonequilibrium Carrier Dynamics in Semiconductors, *Berlin, Germany*. HCIS-10, H. Krüger, Max-Born-Inst., Rudower Chaussee 6, D-12489 Berlin, Germany; fax 49-30-6392-1409; e-mail hcisx@mbi.fta-berlin.de.

AUGUST 1997

3-8 8th European Conf. on Diamond, Diamond-Like, and Related Materials, and 4th Intl. Conf. on Applications of Diamond Films and Related Materials, *Edinburgh, Scotland*. Diamond 1997 Conf. Secretariat, 22 Plas Taliesin, Portway Village Marina, Penarth CF64 1TN, Wales, UK; 44-1222-700053; fax 44-1222-700665; e-mail enquiries@global-meeting.co.uk; <http://www.global-meeting.co.uk>.

3-8 Thermal Spray Processing of Nanoscale Materials, *Davos, Switzerland*. Engineering Foundation, 345 E. 47th St., New York, NY 10017; 212-705-7836; fax 212-705-7441; e-mail engfnd@aol.com; <http://www.engfnd.org>.

10-14 Annual Meeting of the Microscopy Society of America, Microbeam Analysis Society, and The Histochemical Society, *Cleveland, OH*. Microscopy Society of America Business Office, 800-538-3672; fax 508-563-1211; e-mail BusinessOffice@MSA.microscopy.com; <http://www.msa.microscopy.com>.

11-21 NATO Advanced Study Inst. on Nanostructured Materials: Science and Technology, *St. Petersburg, Russia*. G-M. Chow, U.S. Naval Research Lab., Materials Science and Technology Div., Code 6323, Washington, DC 20375; 202-767-3433; fax 202-767-2623; e-mail gmchow@anvil.nrl.navy.mil.

17-20 Intl. Symposium on Materials Solutions for Environmental Problems, *Sudbury, Canada*. H. Mostaghaci, Advanced Materials and Plastics Branch, Industry Canada, 235 Queen St., Ottawa, Ontario K1A 0H5, Canada; 613-954-5012; fax 613-952-4209; e-mail mostaghaci.hamid@ic.gc.ca.

17-21 1997 Intl. Conf. on Neutron Scattering, *Toronto, Canada*. P.H. Green, Solid State Div., Oak Ridge National Lab., P.O. Box 2008, Oak Ridge, TN 37831-6033; 423-576-1864; fax 423-574-4143; e-mail phg@ornl.gov; <http://www.physics.utoronto.ca/icns/icns.html>.

24-29 9th Intl. Meeting on Ferroelectricity, *Seoul, Korea*. IMF-9 Secretariat, INTERCOM Convention Service, Inc., 4Fl., Jisung Bldg., #645-20, Yoksam 1-dong, Kangnam-ku, Seoul, 135-081, Korea; 82-2-568-3208; fax 82-2-565-2434; e-mail intercom@soback.kornet.nm.kr.

25-28 16th General Conf. on the Condensed Matter Division of the European Physical Society, *Leuven, Belgium*. The Secretary-General, 16th CMD-General Conf., Dept. Natuurkunde K. U. Leuven, Celestijnenlaan 200 D, B-3001 Leuven, Belgium; 32-16-327175; fax 32-16-327983.

25-29 8th Intl. Conf. on II-VI Compounds, *Grenoble, France*. L.S. Dang, II-VI Conf. Secretariat, Lab. de Spectrométrie Physique, Univ. J. Fourier, Grenoble, B.P. 87, 38402 St. Martin d'Hères Cedex, France; fax 33-0476-514544; e-mail lesidang@spectro.grenet.fr; http://www.spectro.grenet.fr/~icc_2_6.

26-29 ▼ 16th Intl. Conf. on Thermoelectrics, *Dresden, Germany*. J. Schumann, ICT '97 Technical Program Chairman, Inst. of Solid State and Materials Research, Helmholtzstr. 20, D-01069 Dresden, Germany; 49-351-4659643; fax 49-351-4659780; e-mail ict97@ifw-dresden.de.

27-29 4th Intl. Conf. on Computational Modeling of Free and Moving Boundary Problems, *Ghent, Belgium*. S. Owen, Moving Boundaries 97 Conf. Secretariat, Wessex Inst. of Technology, Ashurst Lodge, Ashurst, Southampton SO40 7AA, UK; 44-1-703-293223; fax 44-1-703-292853; e-mail sue@wessex.ac.uk; <http://www.wessex.ac.uk>.

28-2 ▼ Advanced Quantum Field Theory, *La Londe les Maures, France*. J. Hendekovic, European Science Foundation, 1 quai Lezay-Marnésia, 67080 Strasbourg Cedex, France; 33-388-767135; fax 33-388-366987; e-mail euresco@esf.org; <http://www.esf.org/euresco>.

31-5 14th Intl. Symposium on Chemical Vapor Deposition/EuroCVD Eleven, *Paris, France*. Electrochemical Society; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; <http://www.electrochem.org>. Endorsed.

31-5 Intl. Conf. on Silicon Carbide, III-Nitrides, and Related Materials, *Stockholm, Sweden*. Stockholm Convention Bureau, ICSIII—N'97, P.O. Box 6911, S-102 39 Stockholm, Sweden.

SEPTEMBER 1997

1-5 Intl. Conf. on Crystallographic Texture and Mechanical Anisotropy, *Hyannis, MA*. Engineering Foundation, 345 E. 47th St., New York, NY 10017; 212-705-7836; fax 212-705-7441; e-mail engfnd@aol.com; <http://www.engfnd.org>.

1-12 NATO Advanced Study Inst. on Gap Symmetry and Fluctuations in High-T_c Superconductors, *Corse, France*. D. Pavuna; 41-21-6933301; fax 41-21-6934666; e-mail pavuna@eldp.epfi.ch.

4-7 5th Nepcon Thailand Intl. Electronics Manufacturing Technology Trade Exhibition and Conf., *Bangkok, Thailand*. R. Suksirivong, Reed Tradex Co., Reed Tradex Bldg., 323 Bond St., Muang Thong Thani, Nonthaburi 11120, Thailand; 66-2-503-2199; fax 66-2-503-4963.

5-10 ▼ Molecular Liquids: Orientational Order and Dynamics in Liquids and Glasses, *Crete, Greece*. J. Hendekovic, European Science Foundation, 1 quai Lezay-Marnésia, 67080 Strasbourg Cedex, France; 33-388-767135; fax 33-388-366987; e-mail euresco@esf.org; <http://www.esf.org/euresco>.

6-11 ▼ Chemistry and Physics of Multifunctional Materials: Fullerenes in Context, *Espinho, Portugal*. J. Hendekovic, European Science Foundation, 1 quai Lezay-Marnésia, 67080 Strasbourg Cedex, France; 33-388-767135; fax 33-388-366987; e-mail euresco@esf.org; http://www.esf.org/euresco.

7-10 6th Intl. Conf. on Ceramic Processing, *Santa Barbara, CA*. F.F. Lange, MRL, ENG II, Univ. of California at Santa Barbara, Santa Barbara, CA 93106; e-mail ceramics@mrl.ucsb.edu.

7-10 7th Intl. Conf. on Defect Recognition and Image Processing in Semiconductors, *Berlin, Germany*. DRIP VII Secretary, Ferdinand-Braun-Inst., Rudower Chaussee 5, D-12489 Berlin, Germany; 49-30-63922642; e-mail DRIPVII-fbh-ikz@fbh.fta-berlin.de.

7-11 24th Intl. Symposium on Compound Semiconductors, *San Diego, CA*. M. Melloch, Purdue Univ., 1285 Electrical Engineering Bldg., W. Lafayette, IN 47907-1285; 317-494-3528; fax 317-494-6441; e-mail melloch@ecn.purdue.edu.

7-20 Summer School on Superconductivity in Networks and Mesoscopic Structures, *Sienna, Italy*. C. Giovannella, Dipartimento di Fisica, Univ. di Roma "Tor Vergata," Via della Ricerca Scientifica 1, I-00133 Rome, Italy; 39-6-72594524; fax 39-6-2023507; e-mail supnet@roma2.infn.it; http://www.was.roma2.infn.it/.

8-10 11th Intl. Conf. on Surface Modification Techniques, *Paris, France*. ASM Intl., Member Services Center, Materials Park, OH 44073-0002; 216-338-5151; fax 216-338-4634; e-mail memserv@po.asm-intl.org.

13-15 3rd Okinaga Symposium on Materials Science and Engineering Serving Society, *Makuhari, Chiba, Japan*. S. Sōmiya, Teikyo Univ. of Science and Technology, 3-4-7 Seijo, Setagaya, Tokyo 157, Japan; 81-554-634411; fax 81-3-3415-6619.

13-18 ▼ Quantum Optics, *Castelvecchio Pascoli, Italy*. J. Hendekovic, European Science Foundation, 1 quai Lezay-Marnésia, 67080 Strasbourg Cedex, France; 33-388-767135; fax 33-388-366987; e-mail euresco@esf.org; http://www.esf.org/euresco.

14-18 ASM/TMS Materials Week and Materials Exposition; 17th ASM Heat Treating Society Conf.; and ASM Thermal Spray Society and DVS (German Welding Society) United Thermal Spray Conf.; *Indianapolis, IN*. ASM Intl., Member Services Center, Materials Park, OH 44073-0002; 216-338-5151; fax 216-338-4634; e-mail memserv@po.asm-intl.org.

14-18 Conf. on Spectroscopies in Novel Superconductors, *Cape Cod, MA*. J. Pumphrey, Conf. Secretary, The Barnett Inst., Northeastern Univ., Boston, MA 02115; 617-373-2868; fax 617-373-2855.

14-19 Radiation Effects in Insulators—9, *Knoxville, TN*. REI-9 Secretariat, c/o J. Johnson, 100 Estabrook Hall, Univ. of Tennessee, Knoxville, TN 37996-2350; 423-974-0816; 423-974-4995; e-mail jewell@utk.edu.

15-17 Intl. Conf. on Fine Powder Processing, *State College, PA*. Particulate Materials Center, 147 Research Bldg. West, The Pennsylvania State Univ., University Park, PA 16802-6809; 814-863-6156; fax 814-863-9704; e-mail rgc5@psu.edu; http://pmcenter.cerse.psu.edu.

15-19 ▼ 2nd Yugoslav Conf. on Advanced Materials, *Herceg Novi, Yugoslavia*. P. Živanović, Conf. Secretary, Inst. of Technical Sciences of the Serbian Academy of Sciences and Arts, Knez Mihailova 35/IV, P.O. Box 745, 11000 Belgrade, Yugoslavia; 381-11-185437; fax 381-11-185263.

16-18 4th IUMRS Intl. Conf., *Chiba, Japan*. Y. Masahiro, Materials and Structures Lab., Tokyo Inst. of Technology, 4259 Nagatsuta, Midori, Yokohama 226, Japan; 81-45-924-5323; fax 81-45-924-5358; e-mail iumrs1@riem.titech.ac.jp. **IUMRS.**

20-25 ▼ Very High Resolution Spectroscopy with Photoelectrons: Basic Processes and Applications, *Emmetten, Switzerland*. J. Hendekovic, European Science Foundation, 1 quai Lezay-Marnésia, 67080 Strasbourg Cedex, France; 33-388-767135; fax 33-388-366987; e-mail euresco@esf.org; http://www.esf.org/euresco.

21-24 Midwestern Mechanics Conf., *Rapid City, SD*. L. Kjerengtroen, S. Dakota School of Mines and Technology, Dept. of Mechanical Engineering, Rapid City, SD 57701; 605-394-2409; fax 605-395-2405; e-mail lkjereng@mmsmailgw.sdsmt.

21-25 5th Intl. Symposium on Advanced Materials, *Islamabad, Pakistan*. Secretariat, A.Q. Khan Research Laboratories, P.O. Box 905, Rawalpindi, Pakistan; 92-51-450734; fax 92-51-452487; e-mail 100074.172@compuserve.com.

21-26 2nd Intl. Symposium on Structural Intermetallics, *Champion, PA*. B. Kamperman, The Minerals, Metals & Materials Society, 420 Commonwealth Dr., Warrendale, PA 15086; 412-776-9000; ext. 234; fax 412-776-3770; e-mail kamperman@tms.org.

21-26 10th Intl. Conf. on Surface Modification of Metals by Ion Implantation, *Gatlinburg, TN*. SMMIB-97, Attn.: V. Barnes, Oak Ridge Natl. Lab., Bldg. 3137, M.S. 6057, Oak Ridge, TN 37831-6057; e-mail smmib@ornl.gov.

21-26 ▼ Dynamical Properties of Solids, *Davos, Switzerland*. J. Hendekovic, European Science Foundation, 1 quai Lezay-Marnésia, 67080 Strasbourg Cedex, France; 33-388-767135; fax 33-388-366987; e-mail euresco@esf.org; http://www.esf.org/euresco.

23-26 ▼ 1997 Ceramic Industry Manufacturing Conf., *Columbus, OH*. C. Hyland, Ceramic Industry, 5900 Harper Rd., Ste. 109, Solon, OH 44139; fax 216-498-9121; http://www.ceramics.com/ci.

23-28 ▼ Particle-Solid Interactions: Strong Perturbations, *San Sebastian, Spain*. J. Hendekovic, European Science Foundation, 1 quai Lezay-Marnésia, 67080 Strasbourg Cedex, France; 33-388-767135; fax 33-388-366987; e-mail euresco@esf.org; http://www.esf.org/euresco.

28-1 Eastern Regional Conf. on Crystal Growth and Epitaxy, *Atlantic City, NJ*. R. Scripa, Univ. of Alabama at Birmingham, Dept. of Materials Engineering, 1150 10th Ave. South, Birmingham, AL 35294-4461; 205-934-8453; fax 205-934-8485; e-mail rscripa@eng.uab.edu.

28-3 MRS'97 Scientific Basis for Nuclear Waste Management, *Davos, Switzerland*. NAGRA, V. Schatzmann, Hardstrasse 73, 5430 Wetztingen, Switzerland; 41-56-437-12-53; fax 41-56-437-12-07; e-mail mrs97@nagra.ch. **MRS.**

29-30 Annual Canadian Univ./Crown Labs/Industry Technology Transfer Conf., *Edmonton, Alberta, Canada*. L.W. Sircy, Technology Transfer Conferences, Inc., 325 Plus Park Blvd., #108, Nashville, TN 37217; 615-366-0679; fax 615-366-0695.

29-1 2nd European Meeting on Integrated Ferroelectrics, *Jouy-en-Josas, Campus Thomson, France*. EMIF2 Secretariat, Groupe Francais de la Céramique, 47 à 73, Ave. Albert Thomas, 87065 Limoges Cedex, France; fax 33-5-55790998; e-mail jf.baumard@ensci.fr.

OCTOBER 1997

1-2 ▼ OEM Electronics Conf., *Boston, MA*. D. Waltersdorf, Exposition Excellence Corp., 112 Main St., Norwalk, CT 06851; 203-847-9599; fax 203-854-9438.

5-8 16th North American Conf. on Molecular Beam Epitaxy, *Ann Arbor, MI*. P. Bhattacharya, Conf. Chair, Univ. of Michigan, Dept. of EE&CS, 1301 Beal Ave., Ann Arbor, MI 48109; 313-763-6678; e-mail pkb@eecs.umich.edu.

5-8 Julian Szekely Memorial Symposium on Materials Processing, *Cambridge, MA*. TMS Customer Service Dept., 420 Commonwealth Dr., Warrendale, PA 15086; 412-766-9000; fax 412-776-3770; e-mail csc@tms.org.

6-8 12th Annual Technical Conf. of the American Society for Composites, *Dearborn, MI*. A. Duffer, Conf. Secretary, Mechanical Engineering Dept., Wayne State Univ., Detroit, MI 48202; 313-577-3877; fax 313-577-8789; e-mail gnewaz@eng.wayne.edu.

6-10 11th Intl. Conf. on Photopolymers and Intl. Conf. on Polyimides and Other Low K Dielectrics, *McAfee, NJ*. M.M. Khojasteh, IBM Corp., Microelectronics Div., 8/300-40E, 1580 Rt. 52, Hopewell Junction, NY 12533; 914-894-5458; fax 914-892-6256; e-mail mkhojasteh@vnet.ibm.com.

8 ▼ Intl. Symposium on Solar Chemistry, *Villigen, Switzerland*. T. Daum, Secretariat, Solar Chemistry Symposium, Paul Scherrer Inst., CH-5232 Villigen PSI, Switzerland; 41-56-3102896; fax 41-56-3102199; e-mail cdaum@psi.ch.

11-17 OSA Annual Meeting, *Long Beach, CA*. Meetings Dept., Optical Society of America, 2010 Massachusetts Ave. NW, Washington, DC 20036-1023; 202-223-0920; fax 202-416-6100.

12-15 49th Pacific Coast Regional Meeting and American Ceramic Society Basic Science Division Meeting, *San Francisco, CA*. Customer Service Dept., American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-794-5890; fax 614-899-6109; e-mail customersvc@acers.org.

12-16 30th Intl. Symposium on Microelectronics, *Philadelphia, PA*. ISHM'97/Intl. Microelectronics and Packaging Society, 1850 Centennial Park Dr., Ste. 105, Reston, VA 20191-1517; 703-758-1060; 703-758-1066; e-mail IMAPS@aol.com.

13-15 5th Intl. Symposium on Brittle Matrix Composites, *Warsaw, Poland*. A.M. Brandt, IFTR, Swietokrzyska 21, 00-049 Warsaw, Poland; fax 48-22-269815; e-mail abrandt@ippt.gov.pl.

14-16 ACeRS Electronics Div. Meeting with the Intl. Microelectronics and Packaging Society, *Philadelphia, PA*. Customer Service Dept., American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-794-5890; fax 614-899-6109; e-mail customersvc@acers.org; http://www.acers.org.

14-18 Radioactive Waste, Storage, Transportation, Recycling: Environment and Human Impact, *St. Petersburg, Russia*. Shpalernaja str. 49, 193015 St. Petersburg, Russia; 7-812-274-3796; fax 7-812-274-1707; e-mail kkv@promety2.spb.su. **R-MRS, E-MRS.**

20-24 15th Intl. Conf. on Magnet Technology, *Beijing, China*. L. Lin, MT-15 Program Committee, Applied Superconductivity Div., Inst. of Electrical Engineering, Chinese Academy of Sciences, P.O. Box 2703, Beijing 100080, P.R. China; 86-10-6256-1492; fax 86-10-6256-0904; e-mail asd@piano.iee.ac.cn.

20-24 ▼ 44th American Vacuum Society National Symposium, *San Jose, CA*. A. Mulligan, American Vacuum Society, 120 Wall St., 32nd Floor, New York, NY 10005; 212-248-0200; fax 212-248-0245; e-mail angela@vacuum.org; http://www.vacuum.org.

21-23 ▼ 1997 U.S. Workshop on Physics and Chemistry of II-VI Materials, *Santa Barbara, CA*. M. Goldfarb, 1997 II-VI Workshop, Palisades Inst. for Research Services, Inc., 201 Varick St., Ste. 1006, New York, NY 10014; 703-413-3891; fax 703-413-1315; e-mail mgoldfar@washington.palisades.org.

21-23 Medical Equipment Design and Technology Conf., *Amsterdam, The Netherlands*. Canon Communications, Inc., 3340 Ocean Park Blvd., Ste. 1000, Santa Monica, CA 90405-3216; 310-392-5509; fax 310-392-1557; http://www.cancom.com.

U.K. Dialing Codes: North American callers to England, Northern Ireland, Scotland, and Wales need to insert an additional "1" directly after "44," the U.K. Country Code. For example, North Americans calling London will dial "44-1-71" prior to the local number.

24-31 American Ceramic Society Glass and Optical Materials Division Joint Meeting with the Optical Society of America, *Williamsburg, VA*. Customer Service Dept., American Ceramic Society, P. O. Box 6136, Westerville, OH 43086-6136; 614-794-5890; fax 614-899-6109; e-mail customersvc@acers.org.

27-31 2nd Intl. Conf. on Nitride Semiconductors, *Tokushima, Japan*. S. Yoshida, ICNS'97, Materials Science Div., Electrotechnical Lab., 1-1-4 Umezono, Tsukuba, Ibaraki 305, Japan; 81-298-54-5222; fax 81-298-58-5434; e-mail syoshida@etl.go.jp; <http://www-icns.ee.tokushima-u.ac.jp>.

27-31 23rd Intl. Symposium for Testing and Failure Analysis, *Santa Clara, CA*. ASM Intl., Member Services Center, Materials Park, OH 44073-0002; 216-338-5151; fax 216-338-4634; e-mail memserv@po.asm-intl.org.

27-31 Joint Magneto-Optical Recording Intl. Symposium and Intl. Symposium on Optical Memory, *Yamagata, Japan*. Secretariat for the Joint MORIS/ISOM '97, c/o Business Center for Academic Societies Japan, 5-16-9 Honkomagome, Bunkyo-ku, Tokyo 113, Japan; 81-3-5814-5800; fax 81-3-5814-5823.

29-1 Annual Convention of the Composites Fabricators Association and the Society for the Advancement of Material and Process Engineering, *Orlando, FL*. M. Henriksen, COMPOSITES 97, Composites Fabricators Association, 8201 Greensboro Dr., Ste. 300, McLean, VA 22102; 703-610-9025; fax 703-610-9005; e-mail cfa.info@cfa.hq.org.

NOVEMBER 1997

4-8 Unified Intl. Technical Conf. on Refractories, *New Orleans, LA*. Jerry E. Elliott, The American Ceramic Society, P. O. Box 6136, Westerville, OH 43086-6136; 614-794-5866; fax 614-899-6109; e-mail elliott@acers.org.

16-19 1997 Intl. Conf. on Tungsten, Refractory Metals, and Alloys, *Orlando, FL*. Metal Powder Industries Federation, 105 Colledge Rd. East, Princeton, NJ 08540; 609-452-7700; fax 609-987-8523; e-mail info@mpif.org.

16-21 1997 Congress of the American Society of Mechanical Engineers, *Dallas, TX*. G.J. Wiens, Program Chair, Dept. of Mechanical Engineering, 237 MEB, Univ. of Florida, Gainesville, FL 32611-6300; 904-392-0806; fax 904-392-1071; e-mail gwiens@cimar.me.ufl.edu.

17-18 Midwest Univ. Industry Technology Transfer Conf., *Chicago, IL*. L.W. Sircy, Technology Transfer Conferences, Inc., 325 Plus Park Blvd., #108, Nashville, TN 37217; 615-366-0679; fax 615-366-0695.

17-20 16th Intl. Congress on Applications of Lasers and Electro-Optics, *San Diego, CA*. D. Flynn, Conf. Coordinator, Laser Inst. of America, 12424 Research Pkwy., Ste. 125, Orlando, FL 32826; 407-380-1553; fax 407-380-5588.

DECEMBER 1997

1-5 MRS Fall Meeting, *Boston, MA*. Materials Research Society, 9800 McKnight Rd., Pittsburgh, PA 15237-6006; 412-367-3003; fax 412-367-4373; <http://www.mrs.org/>. MRS.

16-20 9th Intl. Workshop on Physics of Semiconductor Devices, *Delhi, India*. S.K. Agarwal, Secretary, IWPSD-97, Solid State Physics Lab., Lucknow Rd., Timarpur, Delhi-110054, India; 91-11-238739; fax 91-11-2913609; e-mail ska@drsspl.ren.nic.in.

JANUARY 1998

6-9 7th Joint MMM-Intermag Magnetism Conf., *San Francisco, CA*. D. Suiters, Conf. Coordinator, 655 15th St. N.W., Ste. 300, Washington, DC 20005; 202-639-5088; fax 202-347-6109; e-mail magnetism@courtesy.assoc.com.

APRIL 1998

13-17 MRS Spring Meeting, *San Francisco, CA*. Materials Research Society, 9800 McKnight Road, Pittsburgh, PA 15237-6006; 412-367-3003; fax 412-367-4373; <http://www.mrs.org/>. MRS.

26-1 44th Annual Technical Meeting of the Inst. of Environmental Sciences, *Phoenix, AZ*. Inst. of Environmental Sciences, 940 E. Northwest Hwy., Mt. Prospect, IL 60056; 847-255-1561; 847-255-1699; e-mail istenvsci@aol.com.

JUNE 1998

14-19 9th World Ceramics Congress and Forum on New Materials, *Florence, Italy*. CIMTEC '98, P. O. Box 174, 48018 Faenza, Italy; 39-546-663362; fax 39-546-664138; <http://www.dinamica.it/cimtec>.

JULY 1998

12-16 3rd Pacific Rim Intl. Conf. on Advanced Materials and Processing, *Honolulu, HI*. P. Weiss, PRICM 3 Program Coordinator, TMS, 420 Commonwealth Dr., Warrendale, PA 15086-7514; 412-776-9000, ext. 227; fax 412-776-3770; e-mail weissp@tms.org.

AUGUST 1998

24-27 Electroceramics VI, 11th Intl. Symposium on Applications of Ferroelectrics, and 4th European Conf. on Applications of Polar Dielectrics, *Montreux, Switzerland*. ECAPD & ISAF Electroceramics VI, LC-DMX-EPFL, CH-1015 Lausanne, Switzerland; e-mail electro@lc.dmx.epfl.ch; <http://dmxwww.epfl.ch/lc/electro/home.html>.

26-31 12th Intl. Conf. on Crystal Growth, *Jerusalem, Israel*. ICCG 12, c/o Intl. Travel & Congresses Ltd., P. O. Box 29313, Tel Aviv 61292, Israel; 972-3-5102538; fax 972-3-5160604.

SEPTEMBER 1998

13-18 Applied Superconductivity Conf., Palm Desert, CA. Centennial Conferences, 303-499-2299; fax 303-499-2599; e-mail centennial@orci.com.

15-19 4th Intl Conf. on Computer Simulation of Radiation Effects in Solids, *Okayama, Japan*. Y. Yamamura, Okayama Univ. of Science, Ridai-cho, Okayama 700, Japan; 81-86-252-3161; fax 81-86-255-7700; e-mail yama@dap11.ous.ac.jp.

OCTOBER 1998

25-30 Intl. Rare Earths Conf., *Fremantle, Western Australia*. Secretariat, Materials Inst. of Western Australia, 133 Salvado Rd., Wembley, Western Australia 6014; 61-9-387-9590; fax 61-9-383-9639; e-mail RE98@miwa.org.au; <http://www.miwa.org.au/IREC98>.

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Solid State Division
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College of Engineering and Science
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Required qualifications include: (i) demonstrated administrative and leadership ability; (ii) demonstrated research success as evidenced by a sound record in published basic and/or applied research and recognized contributions in his/her field; and (iii) an earned doctorate in textiles, one of the natural sciences, or engineering, and qualification for appointment in a tenure-track position. Send letter of application, names of at least three references and a curriculum vitae, or a letter of nomination, to Dr. Michael S. Ellison, Chair; Director Search and Screening Committee; School of Textiles, Fiber, and Polymer Science; Clemson University; 161 Sirrine Hall, Box 341307; Clemson, SC 29634-1307. Applicant screening will commence June 2, 1997 and will continue until the position is filled.

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